4. The post-CMP brush of claim 3, wherein the surface area of the top surface of each edge nodule is substantially equal to the area encompassed by the top surface of three central protrusions and associated center gaps.

5. The post-CMP brush of claim 1, wherein the edge nodules and central nodules are arranged in axial rows defining axial channels between the rows.

6. The post-CMP brush of claim 1, wherein the edge nodules in at least one of the first and second set of edge nodules include edge nodules having a first length and edge nodules having a second length greater than the first length.

7. The post-CMP brush of claim 6, wherein the edge nodules having the first length and the edge nodules having the second length alternate circumferentially around the body and are aligned adjacent an edge of the body such that the edge nodules having the second length extend farther towards the center region of the body than the edge nodules of the first length.

8. The post-CMP brush of claim 1, wherein the edge nodules in at least one of the first and second set of edge nodules are all of a same length.

9. The post-CMP brush of claim 8, wherein the edge nodules of the same length are disposed circumferentially around the body and alternate being aligned adjacent an edge of the body and being offset further inward on the body.

10. A method of post CMP cleaning of a surface of a semiconductor wafer, the method comprising:

engaging the surface of a rotating wafer with a rotating cylindrical foam roller, the cylindrical foam roller having a first circumferentially extending row of elongate nodules and a second circumferentially extending row of elongate nodules, each circumferentially extending row of elongate nodules extending around the cylindrical foam roller,

each of the nodules having a side surface and an outer wafer engagement surface, each of the elongate nodules oriented at least primarily in an axial direction,

positioning the roller on the wafer such that the row of elongate nodules are positioned having the edge of the wafer engage only the outer wafer engagement surfaces of the elongate nodules and not the side surfaces.

11. The method of claim 10 wherein the row of nodules are each positioned helically on the foam roller.

12. The method of claim 10 further comprising the step of injecting fluid outwardly through the foam roller as the roller is rotating and in engagement with the wafer.

13. A cylindrical foam roller for post CMP cleaning of wafers, the cylindrical foam roller having an axis and a cylindrical outer base surface with a matrixical arrangement of nodules extending from the cylindrical outer surface, the nodules all extending out a uniform distance from the axis, the nodules extending circumferentially around the cylindrical foam roller, each of the nodules oriented with their elongate dimension extending more in an axial direction than a circumferential direction and wherein the nodules are not all of a uniform top surface area, wherein the matrixical arrangement of nodules includes a multiplicity of cylindrical nodules extending radially outward from the outer cylindrical surface of the foam roller.

14. The foam roller of claim ~~10 or~~ 13 wherein each of the elongate nodules has a wafer engagement surface, the wafer engagement surface having a outer perimeter with a racetrack shape.

~~15. The foam roller of claim 10 or 13 or 14 wherein the matrixical arrangement of nodules includes a multiplicity of cylindrical nodules extending radially outward from the outer cylindrical surface of the foam roller.~~

~~16~~15. The foam roller of ~~any of claim 10-15~~ claim 13 or 14 wherein the matrixical arrangement include a circumferentially extending row of cylindrical nodules adjacent to the circumferentially extending elongate nodules, the row of cylindrical nodules interlaced with the row of elongate nodules.

~~17~~16. The foam roller of any of claims ~~10-16~~ 13-15 wherein each of the nodules of the matrixical arrangement of nodules has an outer wafer engagement surface, each of said surfaces being parallel to the cylindrical outer base surface of the foam roller.

~~18~~17. The foam roller of any of claims ~~10-17~~ 13-16 wherein each of the nodules of the matrixical arrangement of nodules has an outer wafer engagement surface and a side surface, each of said surfaces being substantially planar.

~~19~~18. The foam roller of claim 13, wherein each of the nodules is an elongate nodule.